



Material Content Data Sheet



Sales Product Name		SPD03N60C3		Issued		1. August 2018		
MA#		MA000851422						
Package		PG-TO252-3-311		Weight*		314.06 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.326	0.74	0.74	7405	7405
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		137	
	non noble metal	iron	7439-89-6	0.143	0.05		456	
	non noble metal	copper	7440-50-8	143.098	45.53	45.59	455636	456229
	non noble metal	aluminium	7429-90-5	0.534	0.17	0.17	1700	1700
wire	inorganic material	antimonytrioxide	1309-64-4	1.995	0.64		6352	
encapsulation	plastics	brominated resin	-	2.138	0.68		6806	
	organic material	carbon black	1333-86-4	2.280	0.73		7260	
	plastics	epoxy resin	-	19.238	6.13		61254	
	inorganic material	silicondioxide	60676-86-0	116.850	37.21	45.39	372061	453733
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11909	11909
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	275	276
solder	non noble metal	tin	7440-31-5	0.048	0.02		152	
	noble metal	silver	7440-22-4	0.060	0.02		190	
	non noble metal	lead	7439-92-1	2.281	0.73	0.77	7264	7606
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.11	6.12	61063	61142
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com